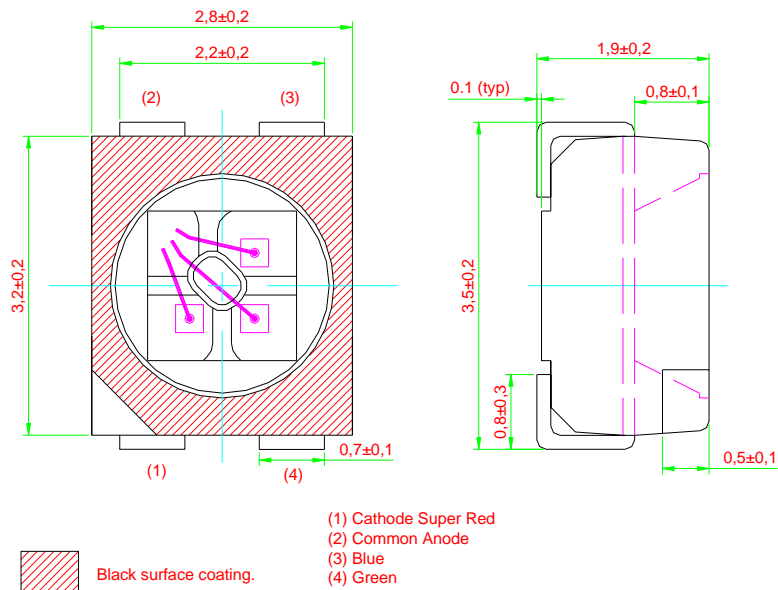




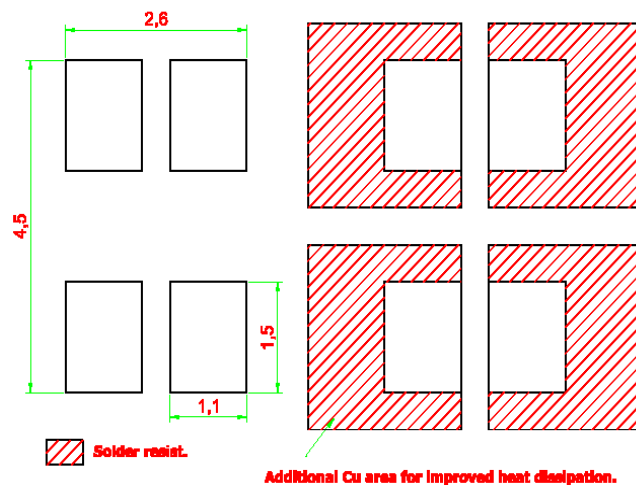
● **Feature:**

1. Low brightness tri-color surface mount LED.
2. Capable for all video-standards. The RGB-LED chips can be controlled separately.
3. 120° viewing angle.
4. Small package outline (LxWxH) of 2.8 x 3.2 x 1.9 mm.
5. Qualified according to JEDEC moisture sensitivity Level 2.
6. Compatible to both IR reflow soldering and TTW soldering.

● **Package Dimension:**



Recommended Solder Pad





● **Optical Characteristics:**

Part Number	Color, λ_{dom} (nm)			Luminous Intensity @ $I_F=10mA$ (mcd)		
	Chip #1	Chip #2	Chip #3	Chip #1	Chip #2	Chip #3
BL-PMSGB-GJB	Super Red	Green	Blue	2.80 – 7.20	7.20 – 18.00	4.50 – 11.20
● BIN H+K+J				2.80 – 4.50	7.20 – 11.20	4.50 – 7.20
● BIN H+K+K				2.80 – 4.50	7.20 – 11.20	7.20 – 11.20
● BIN H+L+J				2.80 – 4.50	11.20 – 18.00	4.50 – 7.20
● BIN H+L+K				2.80 – 4.50	11.20 – 18.00	7.20 – 11.20
● BIN J+K+J				4.50 – 7.20	7.20 – 11.20	4.50 – 7.20
● BIN J+K+K				4.50 – 7.20	7.20 – 11.20	7.20 – 11.20
● BIN J+L+J				4.50 – 7.20	11.20 – 18.00	4.50 – 7.20
● BIN J+L+K				4.50 – 7.20	11.20 – 18.00	7.20 – 11.20

	V_f at $I_f=10mA$		View Angle
	Typ.	Max	
Super Red	1.9	2.6	120
Green	2.1	2.6	
Blue	3.9	4.3	

1. Luminous intensity is measured with an accuracy of $\pm 11\%$.
2. Wavelength binning is also available as an option. Please refer to the following table for details.

● **Absolute Maximum Ratings:**

Parameter	Maximum Value	Unit
DC forward current.	20	mA
Peak pulse current. ($t_p \leq 10 \mu s$, Duty cycle = 0.005)	200	mA
Reverse voltage.	5	V
LED junction temperature.	100	$^{\circ}C$
Operating temperature.	-40 ... +100	$^{\circ}C$
Storage temperature.	-40 ... +100	$^{\circ}C$



● **Wavelength Grouping:**

If wavelength binning is required, only one wavelength group is allowed for each chip within a reel.

Color	Group	Wavelength distribution (nm)
Super Red	Full	620 – 635
Green	Full	565 - 577
	W	565 - 569
	X	569 - 573
Blue	Y	573 – 577
	Full	464 - 476
	W	464 - 468
	X	468 - 472
	Y	472 – 476

Wavelength is measured with an accuracy of ± 1 nm.

● **Typical electro-optical characteristics curves:**

Fig. 1&2 Forward current vs. forward voltage.

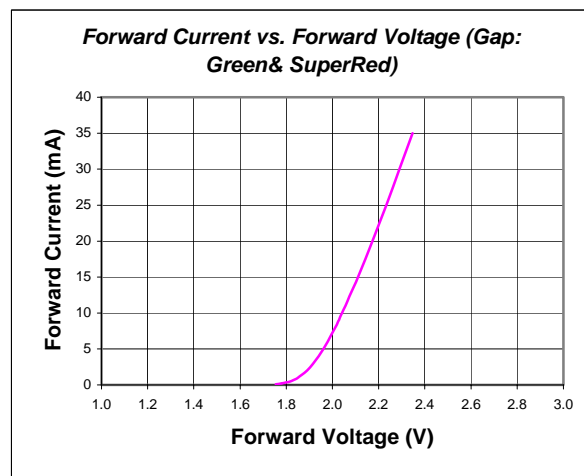
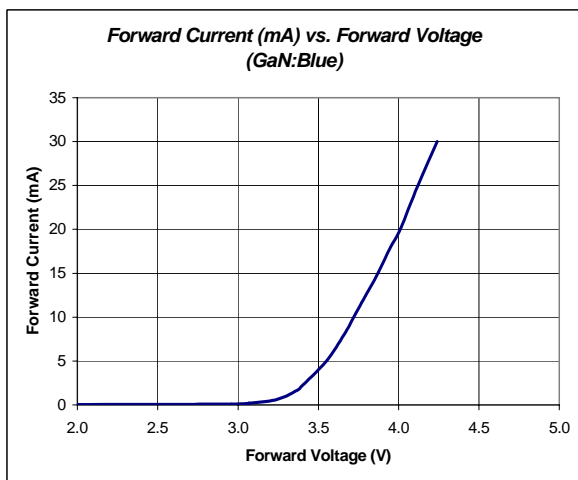


Fig. 3 Radiation pattern.

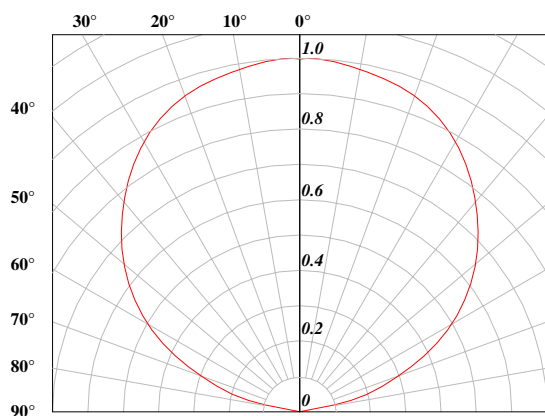


Fig. 4 Maximum forward current vs. ambient temperature

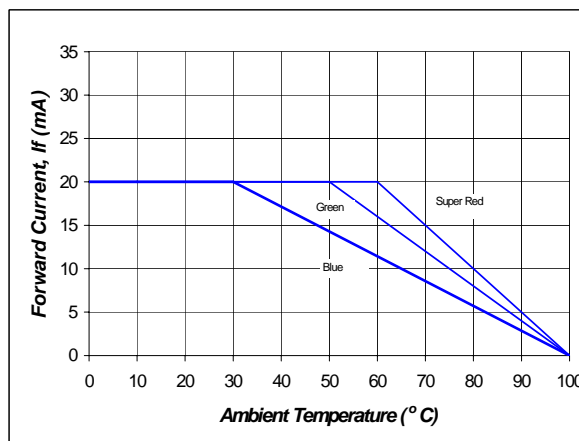




Fig.5 Recommended IR-reflow Soldering Profile (acc. To IPC 9501).

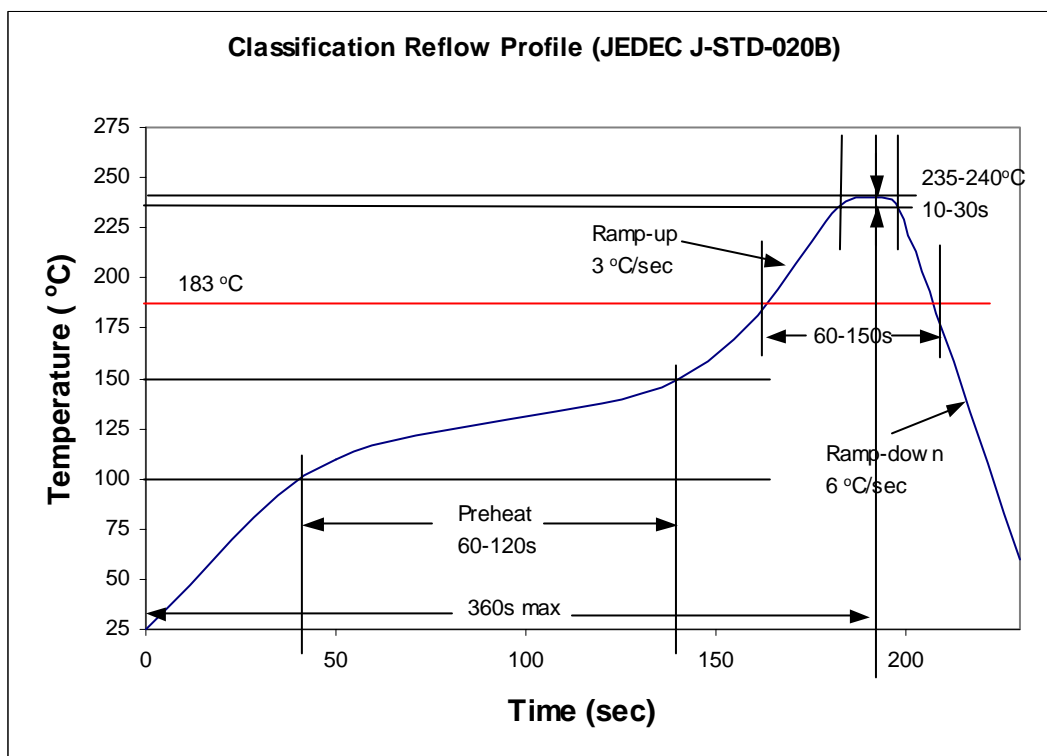


Fig. 6 Recommended TTW Soldering Profile (acc. to CECC 00802).

